

IN THE CLAIMS

Please amend claim 1 to read as follows:

1. A physical property sensor die, comprising:
a substantially solid insulating sensor body having a front surface and a back surface, and
the sensor body having a known thermal conductivity, wherein the sensor body
has a plurality of openings extending from the front surface to the back surface;
a plurality of independent sensing elements coupled to the front surface for monitoring
the properties of a fluid, the plurality of independent sensing elements including
at least one thermal sensor and at least one heater, wherein the thermal
conductivity of the sensor body is low enough to substantially prohibit heat
transfer between the plurality of independent sensing elements via the sensor
body, and wherein the sensor body includes continuous solid material below the
plurality of sensing elements thus providing for a more robust sensor die; and
a connection material filling the plurality of openings such that the plurality of
independent sensing elements are electrically connected to corresponding
connection material on the back surface, and the connection material is configured
to accommodate connection of the connection material to an electronics substrate.

Please add claim 35 as follows:

35. The physical property sensor die of claim 1 wherein the sensor body and the connection
material have a substantially similar coefficient of thermal expansion.
